509 323 8979 TO 17038729306

P.01/12

HEWLETT-PACKARD COMPANY Intellectual Property Administration P. O. Box 272400 Fort Collins, Colorado 80527-2400

PATENT APPLICATION

ATTORNEY DOCKET NO. 10015382-3

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inv ntor():

Buswell et al.

Confirmation N .: 7243

Application No.: 10/601,149

Examiner: Stephens, J.

Filing Date:

06-20-2003

Group Art Unit: 2853

Title:

Slotted Substrate and Method of Making

RECEIVED **CENTRAL FAX CENTER**

Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

MAY 0 3 2004

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

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Response/Amendment

()Petition to extend time to respond

New fee as calculated below

Supplemental Declaration ()

No additional fee (Address envelope to "Mail Stop Non-Fee Amendment")

ffee \$

(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR		(5) PRESENT EXTRA		(6) RATE		(7) ADDITIONAL FEES	
TOTAL CLAIMS	21	1 MINUS 21 =		0	х	\$18	\$	0		
INDEP. CLAIMS	3	MINUS	3		=	0	×	\$86	\$	0
() FIR	ST PRESENTATION OF A	MULTIPLE	DEPENDENT	CLAIM	•		+	\$290	\$	0
EXTENSION FEE	1ST MONTH \$110.00	2ND N \$420	MONTH 3RD MONT 0.00 \$950.00		тн		H MONTH 1480.00		\$	0
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			TOTAL A	DDITIONAL FE	E FOR	THIS AI	MEND	MENT	\$	0

to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

(X) I hereby certify that this paper is being transmitted to the Patent and Trademark Office facsimile number __(703) 872-9306 on. <u>5-63</u> Number of pages: 12

Typed Name: CartinTayl

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PAGE 1/12 * RCVD AT 5/3/2004 1:31:57 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-1/0 * DNIS:8729306 * CSID:509 323 8979 * DURATION (mm-ss):02-28

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Buswell et al.

Examiner:

Stephens, Ju

5 Serial No: 10/601,149

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2853

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7243

Title:

Slotted Substrate and Method of Making

PLL

To:

Commissioner of Patents and Trademarks

PO Box 1450

10

Alexandria, VA 22313-1450

From:

Hewlett-Packard Development Company, L.P

Intellectual Property Administration

P.O. Box 272400

15

Fort Collins, Colorado 80527-2400

INTRODUCTORY COMMENTS

This communication is in response to the Office Action dated 2/10/04, for which a three-month shortened statutory period for response is set for 5/10/04. 20 Please amend the above-identified application in accordance with the directions set forth below.

Amendments to the Specification are reflected on page 2 of this paper.

Amendments to the Claims are reflected on the list of claims which

25 begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.

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